

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
Kouichiro Takashima	02/20/2008
Shun Kayama	02/21/2008
Tsutomu Takahashi	02/21/2008
Yukiko Shimizu	02/20/2008
Hideki Okii	02/22/2008
Takashi Sawada	02/21/2008

**RECEIVING PARTY DATA**

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<b>State/Country:</b>	JAPAN

<b>Name:</b>	Sony Corporation
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**PROPERTY NUMBERS Total: 1**

Property Type	Number
<b>Application Number:</b>	12043262

**CORRESPONDENCE DATA**

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NAME OF SUBMITTER: David R. Metzger

Total Attachments: 3  
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in VIBRATION ASSEMBLY, INPUT DEVICE USING THE VIBRATION ASSEMBLY, AND ELECTRONIC EQUIPMENT USING THE INPUT DEVICE

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY ERICSSON MOBILE COMMUNICATIONS JAPAN, INC., a Japanese corporation with offices at 1-8-15, Konan, Minato-Ku, Tokyo, Japan and Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 12/043,262, Filing Date: 03/06/2008

This assignment executed on the dates indicated below.

Kouichiro TAKASHIMA  
Name of first or sole inventor  
Tokyo, Japan  
Residence of first or sole inventor

Execution date of U.S. Patent Application

Kouichiro Takashima  
Signature of first or sole inventor  
February 20, 2008  
Date of this assignment

Shun KAYAMA

Name of second inventor

Execution date of U.S. Patent Application

Saitama, Japan

Residence of second inventor

SHUN KAYAMA

Feb 21, 2008

Signature of second inventor

Date of this assignment

Tsutomu TAKAHASHI

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Tsutomu Takahashi

Feb 21, 2008

Signature of third inventor

Date of this assignment

Yukiko SHIMIZU

Name of fourth inventor

Execution date of U.S. Patent Application

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Residence of fourth inventor

Yukiko Shimizu

Feb. 20, 2008

Signature of fourth inventor

Date of this assignment

Hideki OKII

Name of fifth inventor

Execution date of U.S. Patent Application

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Residence of fifth inventor

Hideki Okii

Feb. 22, 2008

Signature of fifth inventor

Date of this assignment

Takashi SAWADA

Name of sixth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of sixth inventor

*Takashi Sawada*

*Feb. 21. 2008*

Signature of sixth inventor

Date of this assignment

Name of seventh inventor

Execution date of U.S. Patent Application

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Date of this assignment

Name of eighth inventor

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Residence of eighth inventor

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Date of this assignment

Name of ninth inventor

Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor

Date of this assignment

**PATENT**

**RECORDED: 03/06/2008**

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